



September 11, 2015

Dear Valued Customer:

Re: Change of Name of International Rectifier Corporation

On January 13, 2015, Infineon Technologies AG acquired International Rectifier Corporation. As a follow-up to the acquisition, effective as of October 1, 2015 the name of International Rectifier Corporation (IR) will be changed to

Infineon Technologies Americas Corp.

This is a change in name only, and does not reflect a change in operations, facilities, entity, tax ID or registered address.

- You will continue to be served by your current account manager.
- Your checks should be mailed to the same address, and your wire transfers/ACH should be sent to the same bank account.
- Your shipments will continue to come from the same site.
- You will still deal with the same personnel you currently deal with.

As our customer you are very important to us, and we would like to make this transition as seamless as possible. Should you have any questions or concerns regarding the name change, please contact your IR representative.

We look forward to our strong continued business relationship.

Sincerely,

International Rectifier Corporation

Rainer Matern
Senior Director Accounting,
Controlling & Business Operations

Michael Cortez
Director
Accounting & Treasury

Product / Process Change Notification



Date: Wednesday, November 04, 2015
PCR Reference: 665
PCN Reference: 665-PCN90-Public

To Our Value Customer:

As always we appreciate your use of Infineon Technologies semiconductor products. Our commitment to customer satisfaction and continuous improvement is demonstrated by our change plans to enhance capacity, quality and reliability. This notice is to inform you of the following change:

We would like to express our sincere appreciation for your cooperation regarding the following changes, and Infineon Technologies will work closely with you to support your requirements during this transition.

Type of Change Notification:

Additional site for the assembly and test of PQFN 6x6 30L

Description of Change:

Carsem China has been qualified as additional assembly and test site for the products listed below

Bill of Materials

Material	Carsem Malaysia (Current site)	ASE Malaysia (Current site)	Carsem China (Proposed site)	Impact on Form, Fit or Function
Solder	Pb95Sn5	Pb92.5Sn5Ag2.5	Pb92.5Sn5Ag2.5	None
Wire	Au	Au	Au	None
Source Interconnect	Cu Clip	Cu Clip	Cu Clip	None
Mold compound	G770HCD	G770HCD	G770HCD	None
Terminal Finish	Matte Tin	Matte Tin	NiPdAu	None

Production Route

Current	Proposed
Assembly and Test in Carsem Malaysia	Assembly and Test in Carsem Malaysia
Assembly and Test in ASE Malaysia	Assembly and Test in ASE Malaysia
	Assembly and Test in Carsem China
	Assembly in Carsem China, Test in Carsem Malaysia
	Assembly in Carsem China, Test in ASE Malaysia

Reason for the Change:

Additional assembly and test capacity

Effect Date:

Tuesday, February 02, 2016

Infineon Technologies will consider this change approved and will implement it by the effective date unless specific conditions of acceptance or data requests are provided in writing within 30 days of receipt of this notice. Please submit conditions of acceptance and data requests to the PCN coordinator listed at the end of this notice.

Impact of Change:

No impact is expected. The new Bill of Materials, Assembly and Test site will meet the same parametric, MSL and Qualification level as the existing products. Product Datasheets will remain unchanged.

Method of Identifying Changed Product:

Date Code and Lot Code Information

Products Affected:

IR Part	Description
IR3555AMTRPBF	
IR3555MTRPBF	
IR3556MTRPBF	
IR3557MTRPBF	

Qualification:

Parts passed all the reliability testing requirements. Reliability qualification report is available upon request.

Supporting Data Availability:

Contact Infineon Technologies for supporting data on this change.

Contact Information:

CONTACT TYPE	NAME	PHONE	EMAIL
PCN Coordinator	Mark Ogden	+001-951-375-2334	Mark.Ogden@infineon.com
Technical Contact	Mario Dolores	+6635350803 ext 556	Mario-Antonio.Dolores@infineon.com